

Solder finishes

Surface finish	Material	Layer thickness	Shelf life
HAL lead-free	Sn/Cu/Ni 99.3/0.6/0.1	1 - 40 μm	12 months
chem. Sn	Sn	> 1 μm^*	9 ^{**} /12 months
chem. Ni/Au	Ni/Au	Ni > 3 μm , Au > 0.05 μm	12 months

* Pure tin, coulometrically measured

** With plugged via (IPC 4761 III-a)